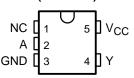
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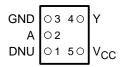
- Available in the Texas Instruments NanoStar™ and NanoFree™ Packages
- Supports 5-V V_{CC} Operation
- Input and Open-Drain Output Accept Voltages up to 5.5 V
- Max t_{pd} of 4.2 ns at 3.3 V
- Low Power Consumption, 10 μ A Max I_{CC}
- ±24-mA Output Drive at 3.3 V
- Ioff Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

DBV OR DCK PACKAGE (TOP VIEW)



NC - No internal connection

YEA OR YZA PACKAGE (BOTTOM VIEW)



DNU - Do not use

description/ordering information

This single buffer/driver is designed for 1.65-V to 5.5-V V_{CC} operation.

NanoStar™ and NanoFree™ package technology is a major breakthrough in IC packaging concepts, using the die as the package.

The output of the SN74LVC1G07 device is open drain and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 32 mA.

This device is fully specified for partial-power-down applications using Ioff. The Ioff circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

TA	PACKAGE [†]	ORDERABLE PART NUMBER	TOP-SIDE MARKING‡	
	NanoStar™ WCSP (DSBGA) – YEA (Lead)	Tape and reel	SN74LVC1G07YEAR	CV
-40°C to 85°C	NanoFree™ WCSP (DSBGA) – YZA (Lead-free)	Tape and reel	SN74LVC1G07YZAR	
	SOT (SOT-23) – DBV	Tape and reel	SN74LVC1G07DBVR	C07_
	SOT (SC-70) – DCK	Tape and reel	SN74LVC1G07DCKR	CV_

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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NanoStar and NanoFree are trademarks of Texas Instruments.



DBV/DCK: The actual top-side marking has one additional character that designates the assembly/test site. YEA/YZA: The actual top-side marking has three preceding characters to denote year, month, and sequence code, and one following character to designate the assembly/test site.

FUNCTION TABLE

IN	IPUT A	OUTPUT Y
	Н	Н
	L	L

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V _{CC}		
Input voltage range, V _I (see Note 1)		0.5 V to 6.5 V
Voltage range applied to any output in the high-	-impedance or power-off state, V _O	
(see Note 1)		0.5 V to 6.5 V
Voltage range applied to any output in the high	or low state, V _O	
(see Notes 1 and 2)		–0.5 V to 6.5 V
Input clamp current, I _{IK} (V _I < 0)		–50 mA
Output clamp current, I _{OK} (V _O < 0)		–50 mA
Continuous output current, IO		±50 mA
Continuous current through V _{CC} or GND		±100 mA
Package thermal impedance, θ_{JA} (see Note 3):	DBV package	206°C/W
37. (DCK package	252°C/W
	YEA/YZA package	154°C/W
Storage temperature range, T _{stg}		65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of V_{CC} is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
Voo	Supply voltage	Operating	1.65	5.5	V	
VCC	Supply voltage	Data retention only	1.5		V	
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}			
V	High lavelings to altern	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V	
VIH	High-level input voltage	V _{CC} = 3 V to 3.6 V	2		V	
		V _{CC} = 4.5 V to 5.5 V	$0.7 \times V_{CC}$			
		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}		
V	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V	
VIL	Low-level input voltage	V _{CC} = 3 V to 3.6 V		0.8	V	
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$		$0.3 \times V_{CC}$		
٧ _I	Input voltage		0	5.5	V	
٧o	Output voltage		0	5.5	V	
		V _{CC} = 1.65 V		4		
		V _{CC} = 2.3 V		8		
loL	Low-level output current	V _{CC} = 3 V		16	mA	
		VCC = 2 ∧		24		
	V _{CC} = 4.5 V			32		
		$V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}, 2.5 \text{ V} \pm 0.2 \text{ V}$		20		
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$		10	ns/V	
		$V_{CC} = 5 V \pm 0.5 V$		5	1	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAI	METER	TEST CONDITIONS	v _{cc}	MIN TYPT MAX	UNIT
		I _{OL} = 100 μA	1.65 V to 5.5 V	0.1	
		I _{OL} = 4 mA	1.65 V	0.45	
.,		I _{OL} = 8 mA	2.3 V	0.3	.,
VOL		I _{OL} = 16 mA	21/	0.4	٧
		I _{OL} = 24 mA	3 V	0.55	
		I _{OL} = 32 mA	4.5 V	0.55	
lį	A input	V _I = 5.5 V or GND	0 to 5.5 V	±5	μΑ
l _{off}		V_I or $V_O = 5.5 V$	0	±10	μΑ
^I CC		$V_I = 5.5 \text{ V or GND}, \qquad I_O = 0$	1.65 V to 5.5 V	10	μΑ
ΔlCC		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 5.5 V	500	μА
C _i		$V_I = V_{CC}$ or GND	3.3 V	4	pF
Co		$V_O = V_{CC}$ or GND	3.3 V	5	pF

 $[\]overline{\dagger}$ All typical values are at V_{CC} = 3.3 V, T_A = 25°C.



SN74LVC1G07 SINGLE BUFFER/DRIVER WITH OPEN-DRAIN OUTPUT

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switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

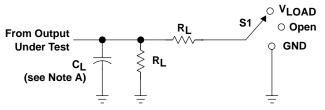
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} = ± 0.1		V _{CC} =		V _{CC} =		V _{CC} =		UNIT
	(1141 01)	(0011 01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	А	Y	2.4	8.3	1	5.5	1.5	4.2	1	3.5	ns

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		DADAMETED	TEST CONDITIONS	V _{CC} = 1.8 V	$V_{CC} = 2.5 V$	$V_{CC} = 3.3 \text{ V}$	V _{CC} = 5 V	UNIT
		FARAIVIETER	TEST CONDITIONS	TYP	TYP	TYP	TYP	CIVII
	C _{pd}	Power dissipation capacitance	f = 10 MHz	3	3	4	6	pF



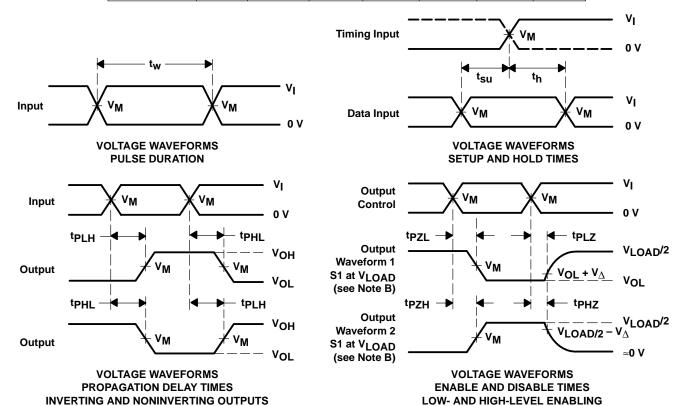
PARAMETER MEASUREMENT INFORMATION (OPEN DRAIN)



TEST	S1
tpzL (see Notes E and F)	V _{LOAD}
tpLZ (see Notes E and G)	VLOAD
tPHZ/tPZH	VLOAD

LOAD CIRCUIT

	INPUT						
vcc	VI	t _r /t _f	VM	VLOAD	CL	RL	$v_{\scriptscriptstyle{\Delta}}$
1.8 V ± 0.15 V	VCC	≤ 2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤ 2 ns	V _{CC} /2	2×VCC	30 pF	500 Ω	0.15 V
3.3 V \pm 0.3 V	3 V	≤ 2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
5 V ± 0.5 V	VCC	≤ 2.5 ns	V _{CC} /2	2×V _{CC}	50 pF	500 Ω	0.3 V



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \Omega$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. Since this device has open-drain outputs, tPLZ and tPZL are the same as tpd.
- F. tpzL is measured at V_M.
- G. t_{PLZ} is measured at $V_{OL} + V_{\Delta}$.
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



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